

点胶式液态导热垫片 XK-S25LV®

Thermal Conductivity Silicone Gel XK-S25LV

特性：

1:1混合（無副產品）

1:1mix(no cure
by-product)

低應力應用

low stress applications

操作方便

Easy to Use

加熱加速反應

Hear Fast Cure



應用：

汽車電子

Automotive
electronics

通訊設施

Telecommunications

電腦及周邊產品

Computer &

peripherals

導熱，減震

Thermally conductive
vibration dampening

熱源與散熱器間應用

Between any
heat-generating
semiconductor and a heat
sink

	XK-S25LV	METHOD	UNIT
Color / Part A	pink	Visual	
Color / Part B	White	Visual	
Features	Soft GEL	-	-
Density	2.9	ASTM D792	g/cm3

Before Cured Property

A:B	1:1	-	-
Mixed Viscosity (20rpm)	300,000	ASTM D2196	Cps
Shelf Life @ 25°C	6 month		

After Cured Property

Color	Pink	Visual	-
Cure Schedule 1	24hr/25°C		
Cure Schedule 2	100min/80°C		
Cure Schedule 3	10min/100°C		
Working time	30 min/25°C		
Hardness	Shore 00 = 70	ASTM D2240	
	AskerC = 30	JIS K7312	
Tensile Strength.	>0.2	ASTM D412	Mpa
Elongation	130	ASTM D412	%
Continuous Use Temp	-60~200		°C

Electrical Property

Dielectric strength	>10	ASTM D149	KV/mm
Volume resistivity	>10 ¹³	ASTM D257	Ohm-cm
Dielectric Constant	8.0	ASTM D150	(1Khz)
Flame Rating	V-0	UL94	

Thermal Property

Thermal Conductivity	2.5	ASTM D5470	W/m*K
Heat Capacity	1.0	ASTM E1269	J/g-K